

CAMPUS® Datasheet

Ultramid® A3EG7 - PA66-GF35
BASF



Product Texts

Glass fibre reinforced injection moulding grade for machinery components and housings with high stiffness and dimensional stability such as lamp socket housings, heating pumps, flow heaters as well as electrically insulating parts.

The products can also be offered as BMBcert™ and/or Ccycled™. Due to the Massbalance approach the product properties do not change.

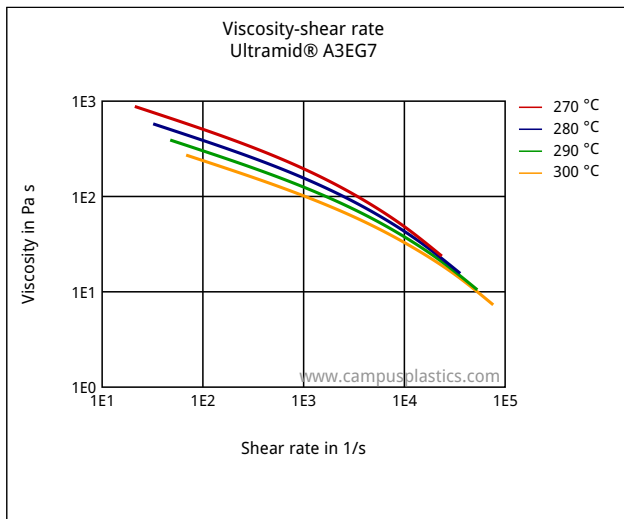
Rheological properties	dry / cond	Unit	Test Standard
Melt volume-flow rate, MVR	30 / *	cm³/10min	ISO 1133
Temperature	275 / *	°C	ISO 1133
Load	5 / *	kg	ISO 1133
Molding shrinkage, parallel	0.5 / *	%	ISO 294-4, 2577
Molding shrinkage, normal	1.0 / *	%	ISO 294-4, 2577
Mechanical properties	dry / cond	Unit	Test Standard
Tensile modulus	11500 / 8500	MPa	ISO 527-1/-2
Stress at break	210 / 150	MPa	ISO 527-1/-2
Strain at break	3 / 5	%	ISO 527-1/-2
Tensile creep modulus, 1000h	* / 6650	MPa	ISO 899-1
Charpy impact strength, +23°C	95 / 107	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	75 / 77	kJ/m²	ISO 179/1eU
Charpy notched impact strength, +23°C	14 / 22	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	12 / -	kJ/m²	ISO 179/1eA
Thermal properties	dry / cond	Unit	Test Standard
Melting temperature, 10°C/min	260 / *	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.80 MPa	250 / *	°C	ISO 75-1/-2
Temp. of deflection under load, 0.45 MPa	260 / *	°C	ISO 75-1/-2
Vicat softening temperature, 50°C/h 50N	250 / *	°C	ISO 306
Coeff. of linear therm. expansion, parallel	22 / *	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	93 / *	E-6/K	ISO 11359-1/-2
Burning behavior at 1.5 mm nominal thickness	HB / *	class	IEC 60695-11-10
Thickness tested (1.5)	1.6 / *	mm	IEC 60695-11-10
Yellow Card available	Yes / *	-	-
Burning behavior at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested (h)	0.8 / *	mm	IEC 60695-11-10
Yellow Card available	Yes / *	-	-
Oxygen index	24 / *	%	ISO 4589-1/-2
Electrical properties	dry / cond	Unit	Test Standard
Relative permittivity, 100Hz	4.3 / 10.1	-	IEC 62631-2-1
Relative permittivity, 1MHz	3.8 / 4.5	-	IEC 62631-2-1
Dissipation factor, 100Hz	120 / 1570	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	210 / 830	E-4	IEC 62631-2-1
Volume resistivity	1E13 / 1E10	Ohm*m	IEC 62631-3-1
Surface resistivity	* / 1E10	Ohm	IEC 62631-3-2
Electric strength	39 / 37	kV/mm	IEC 60243-1
Comparative tracking index	- / 550	-	IEC 60112

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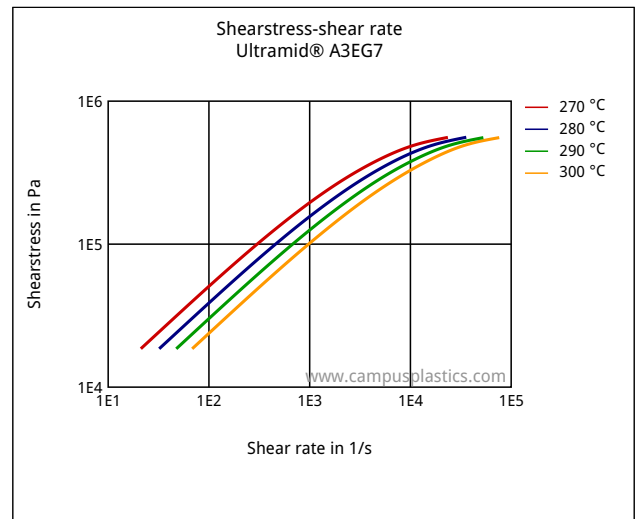
Other properties	dry / cond	Unit	Test Standard
Water absorption	5 / *	%	Sim. to ISO 62
Humidity absorption	1.6 / *	%	Sim. to ISO 62
Density	1410 / -	kg/m³	ISO 1183
Material specific properties	dry / cond	Unit	Test Standard
Viscosity number	145 / *	cm³/g	ISO 307, 1157, 1628
Rheological calculation properties	Value	Unit	Test Standard
Ejection temperature	195	°C	-
Test specimen production	Value	Unit	Test Standard
Injection molding, melt temperature	290	°C	ISO 294
Injection molding, mold temperature	80	°C	ISO 294
Injection molding, injection velocity	200	mm/s	ISO 294

Diagrams

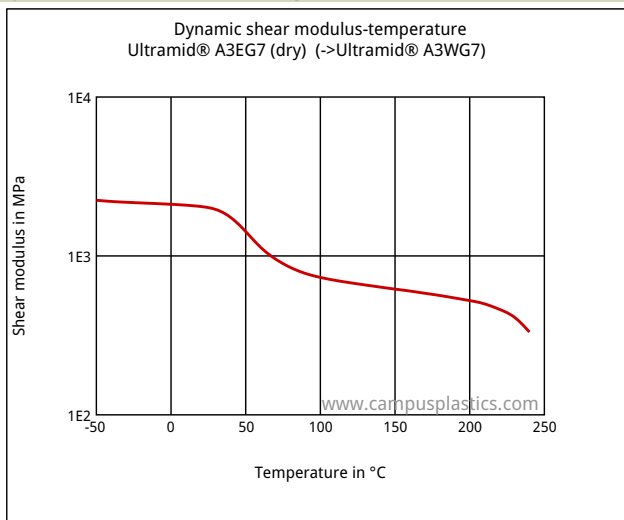
Viscosity-shear rate



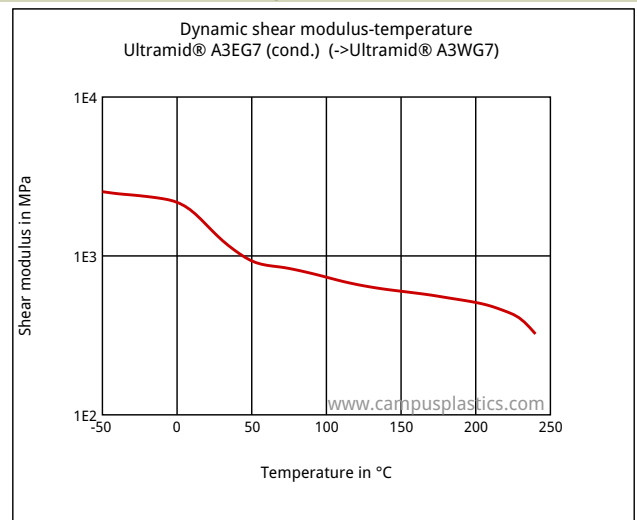
Shearstress-shear rate



Dynamic shear modulus-temperature

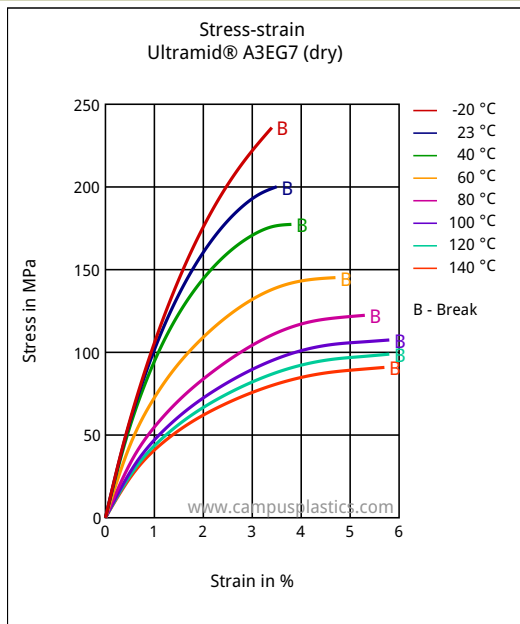


Dynamic shear modulus-temperature

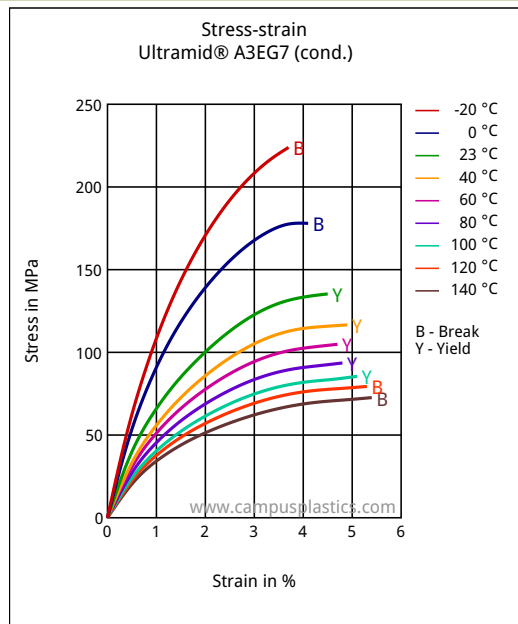


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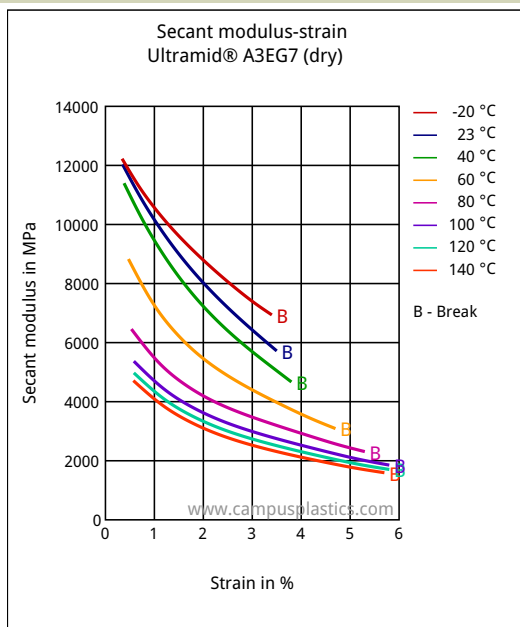
Stress-strain



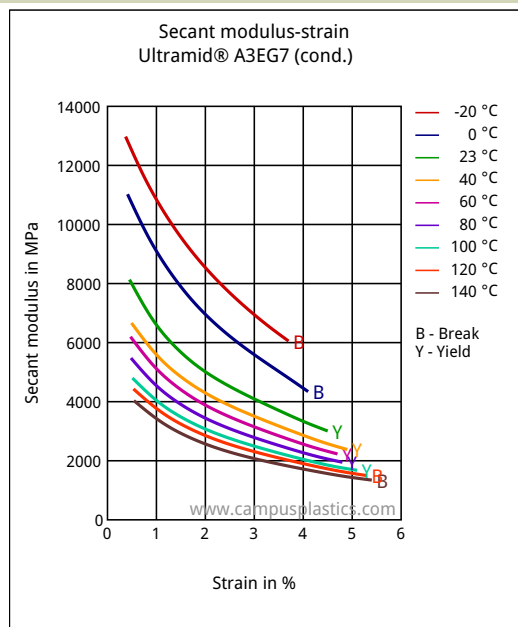
Stress-strain



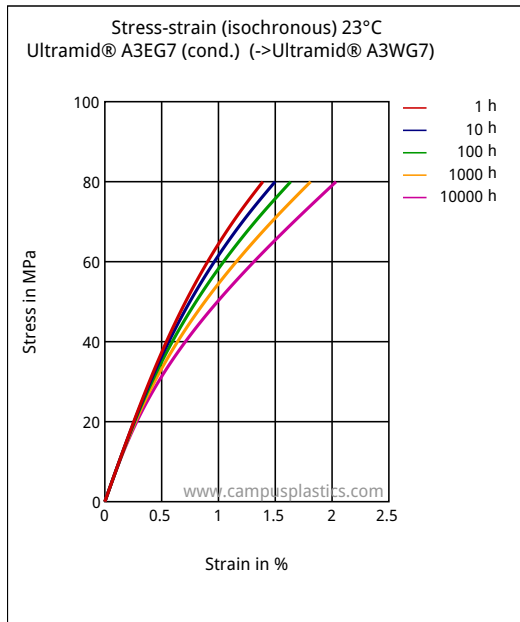
Secant modulus-strain



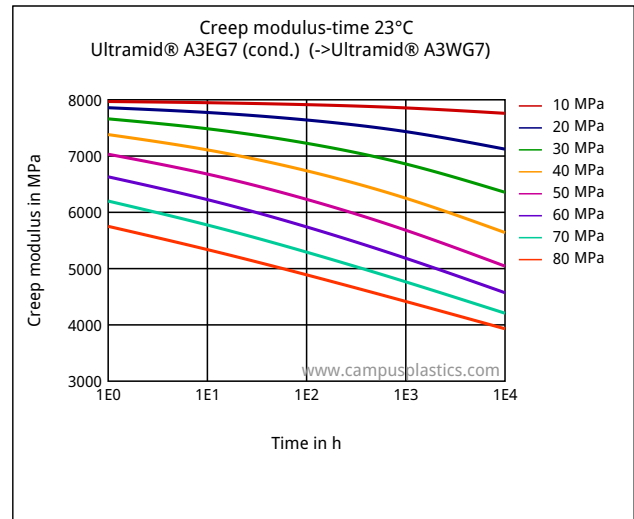
Secant modulus-strain



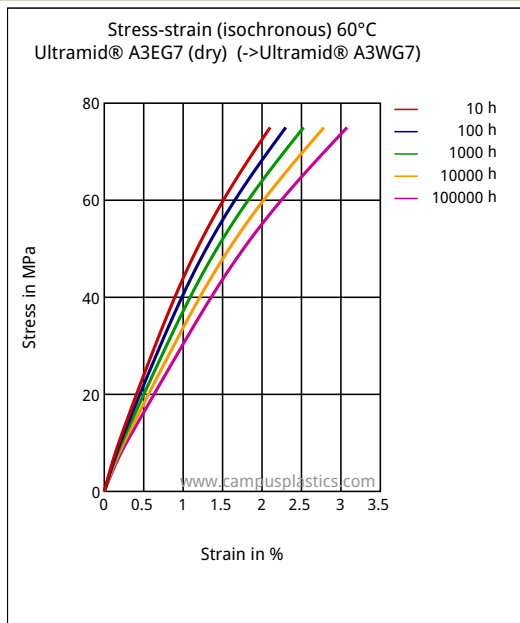
Stress-strain (isochronous) 23°C



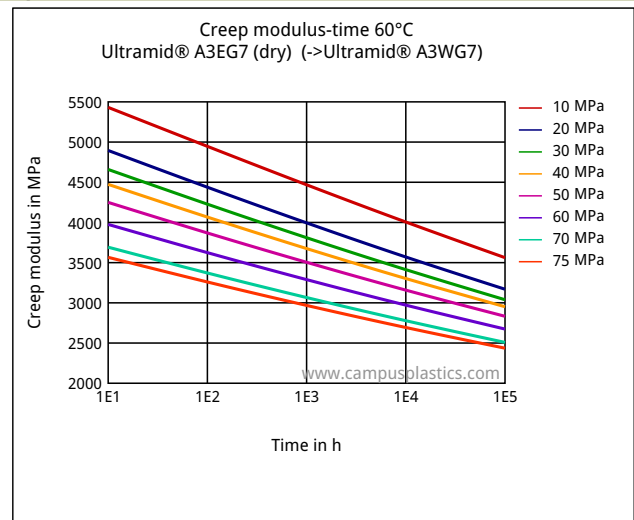
Creep modulus-time 23°C



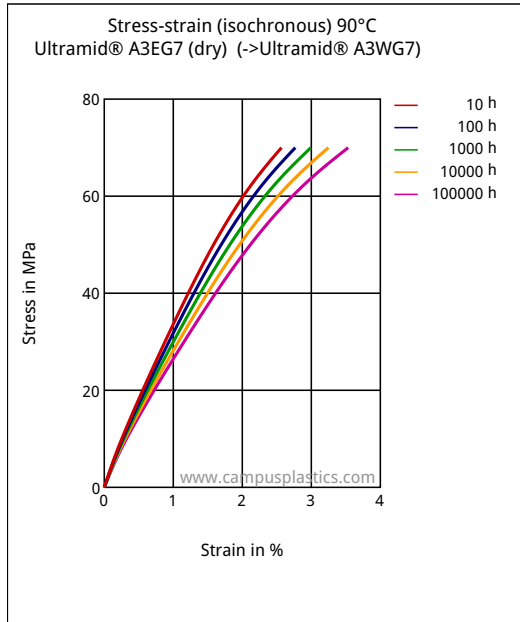
Stress-strain (isochronous) 60°C



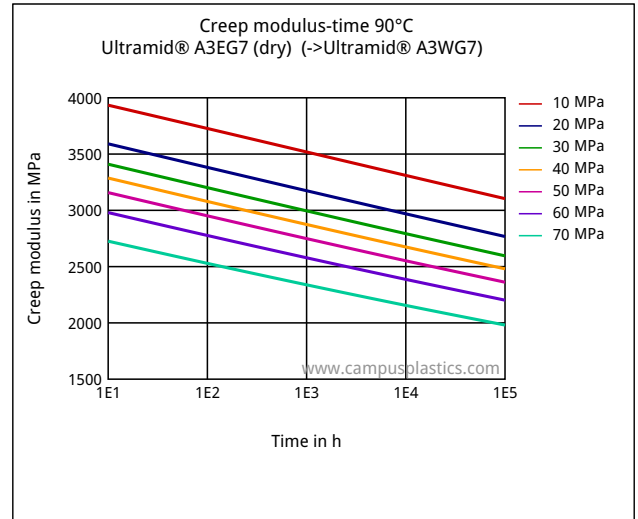
Creep modulus-time 60°C



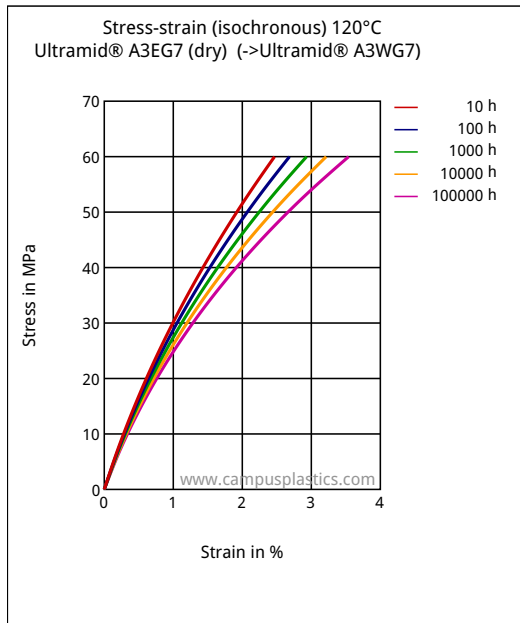
Stress-strain (isochronous) 90°C



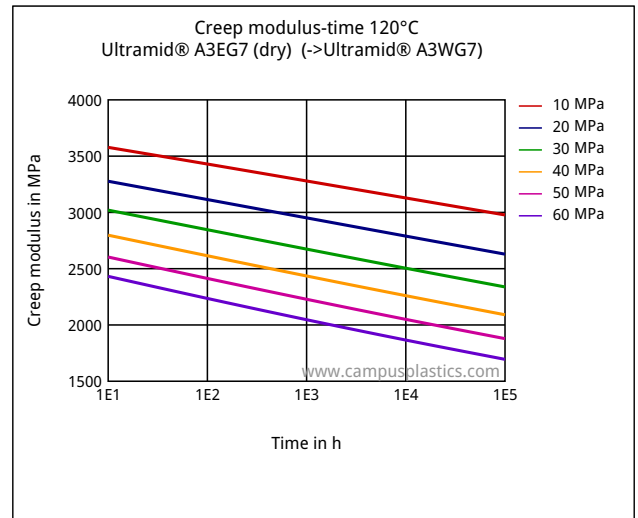
Creep modulus-time 90°C



Stress-strain (isochronous) 120°C

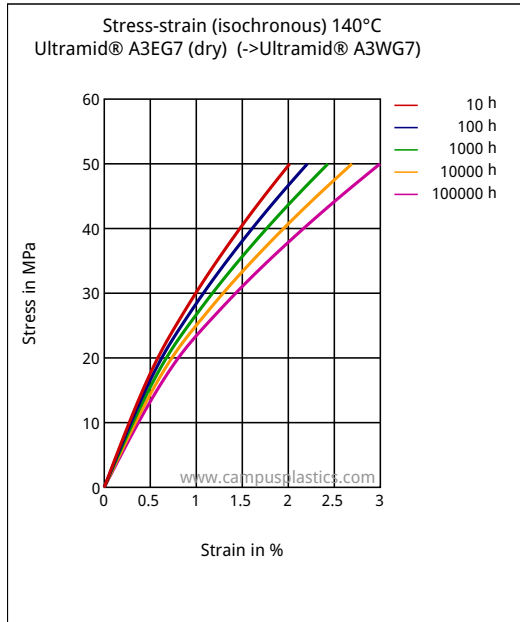


Creep modulus-time 120°C

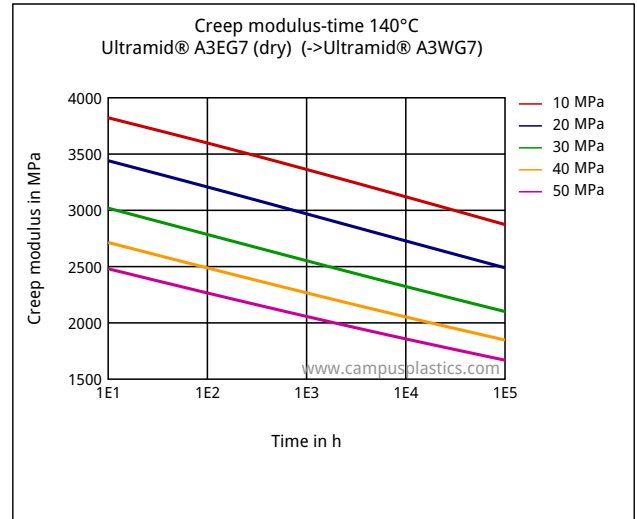


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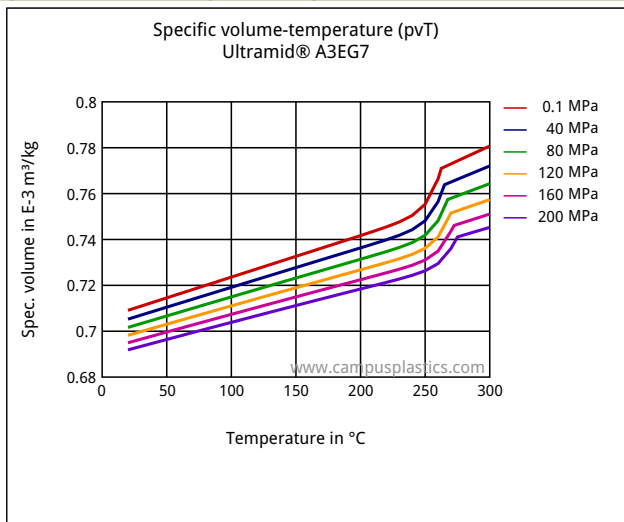
Stress-strain (isochronous) 140°C



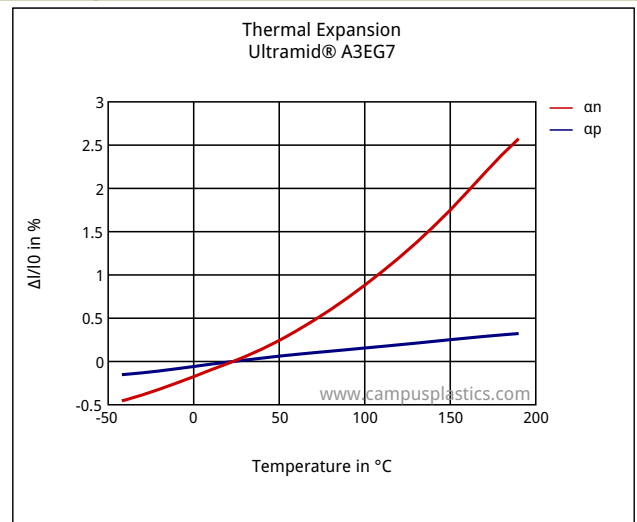
Creep modulus-time 140°C



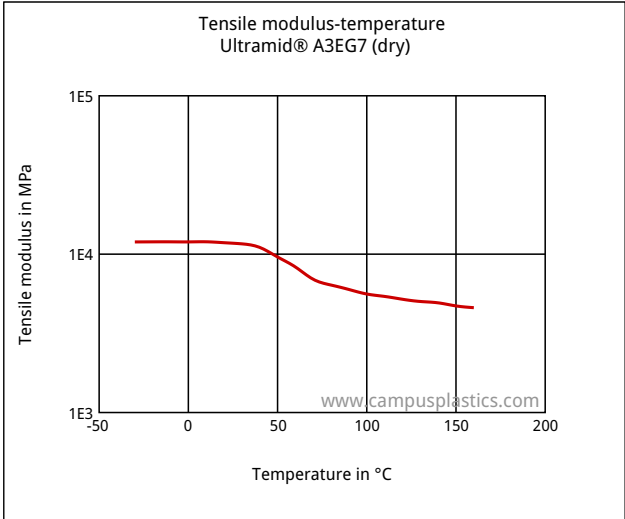
Specific volume-temperature (pvT)



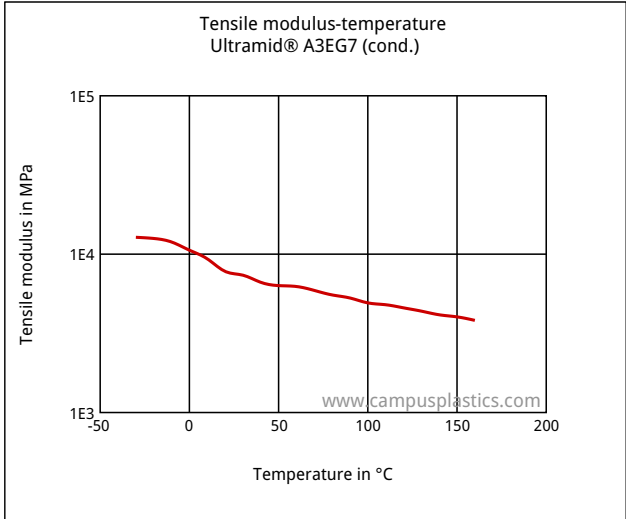
Thermal expansion



Tensile modulus-temperature



Tensile modulus-temperature



Characteristics

Processing

Injection Molding

Delivery form

Pellets

Additives

Lubricants, Release agent

Special Characteristics

Heat stabilized or stable to heat

Regional Availability

North America, Europe, Asia Pacific, South and Central America, Near East/Africa

Other text information

Injection molding

PREPROCESSING

Pre/Post-processing, max. allowed water content: .15 %
 Pre/Post-processing, Pre-drying, Temperature: 80 °C
 Pre/Post-processing, Pre-drying, Time: 4 h

PROCESSING

injection molding, Melt temperature, range: 280 - 300 °C
 injection molding, Melt temperature, recommended: 290 °C
 injection molding, Mold temperature, range: 80 - 90 °C
 injection molding, Mold temperature, recommended: 80 °C
 injection molding, Dwell time, thermoplastics: 10 min

Chemical Media Resistance

Acids



Acetic Acid (5% by mass) (23°C)

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